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(71) Applicant: **HITACHI CHEM CO LTD**

(72) Inventor: **OHORI KENICHI**
HIRAI YASUYUKI
KAMOSHITA SHINICHI
KAKIYA MINORU
ABE NORIHIRO

(54) **FLAME-RETARDANT HEAT-CURABLE RESIN
COMPOSITION, PREPREG USING SAME AND
ELECTRIC WIRING BOARD LAMINATED SHEET**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a nonhalogen- and nonantimony-type heat-curable resin which excels in heat resistance and is useful for wiring boards, a prepreg and a metal clad laminated sheet using the resin.

SOLUTION: A heat-curable resin composition comprises (A) an epoxy resin, (B) a heat-curable resin whose major component is a compound having a dihydrobenzoxazine ring, and (C) a

polycondensate of a phenol, a compound having a triazine ring and an aldehyde and, in addition, (D) 1-50 pts.wt. reactive type phosphorus compound based on 100 pts.wt. total amount of components (A), (B), and (C). The prepreg is obtained by impregnating a substrate with this heat-curable resin composition and drying the resulting impregnated material, and the metal clad laminated sheet is obtained by laminating a metal foil on one side or both sides of this prepreg or a laminate obtained by laying one prepreg on another and subjecting the resulting laminate to heat press molding.

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